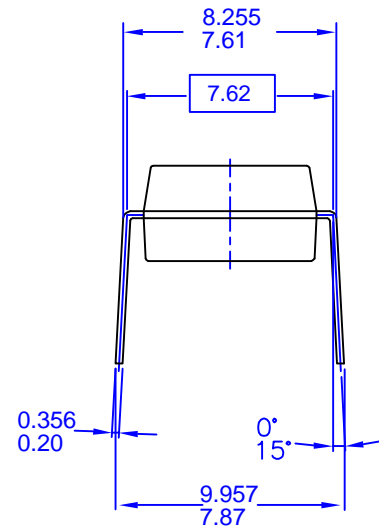
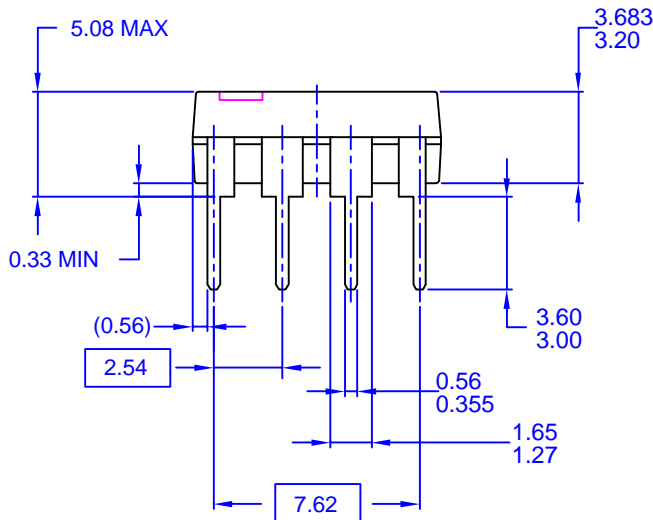
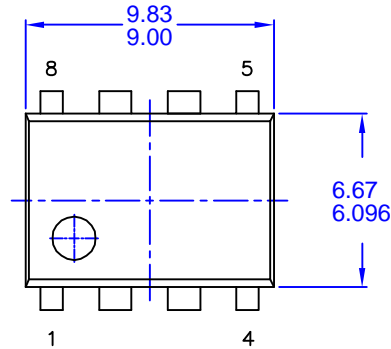


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REVISIONS

LTR	DESCRIPTION	E.D.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL		05APR2004	OS.JEON
2	Dimension Composition	ECN-MKT-N08FR2	2AUG 2007	H.ALLEN



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE CONFORMS TO JEDEC MS-001 VARIATION BA
 - B) ALL DIMENSIONS ARE IN MILLIMETERS.
 - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
 - D) DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994
 - E) DRAWING FILENAME AND REVSION: MKT-N08FREV2.

APPROVALS		DATE	FAIRCHILD SEMICONDUCTOR		
DRAWN: J. H MOON		22MAY2007	8LD, MDIP, JEDEC MS-001 .300" WIDE		
CHECKED: J. H MOON		22MAY2007			
APPROVED: T. S KIM		22MAY2007			
		SCALE 1:1	SIZE NA	DRAWING NUMBER MKT-N08F	REV 2
		FORMERLY: N/A	SHEET : 1 OF 1		